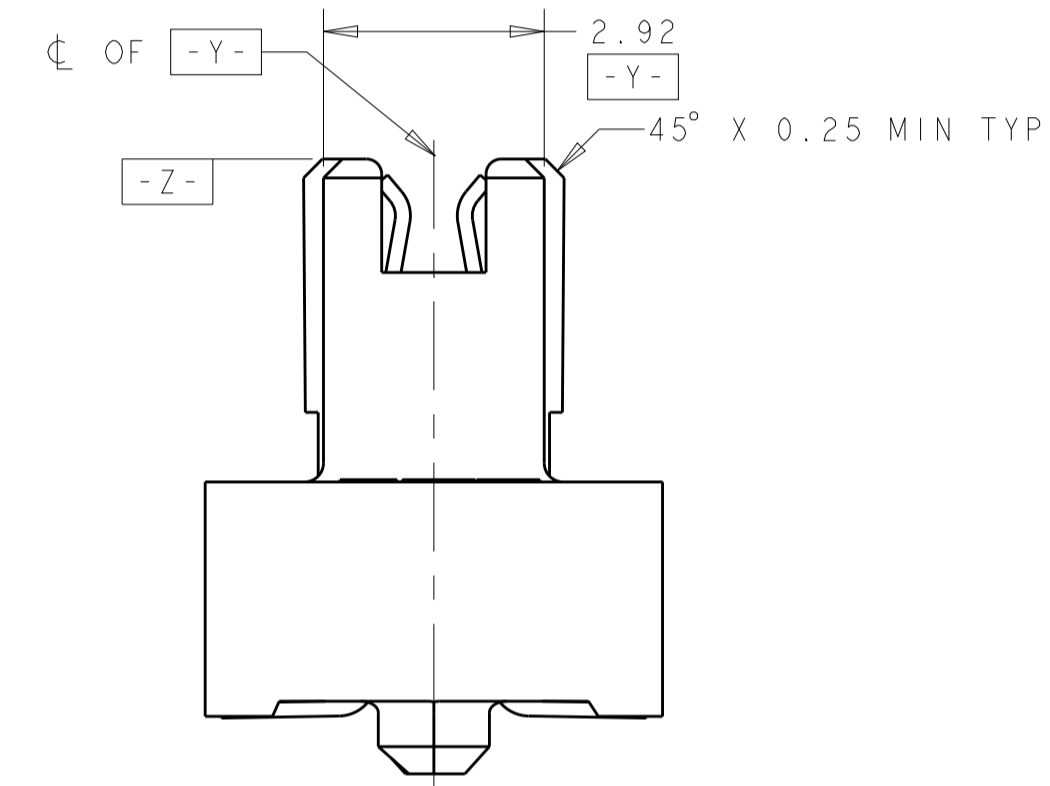
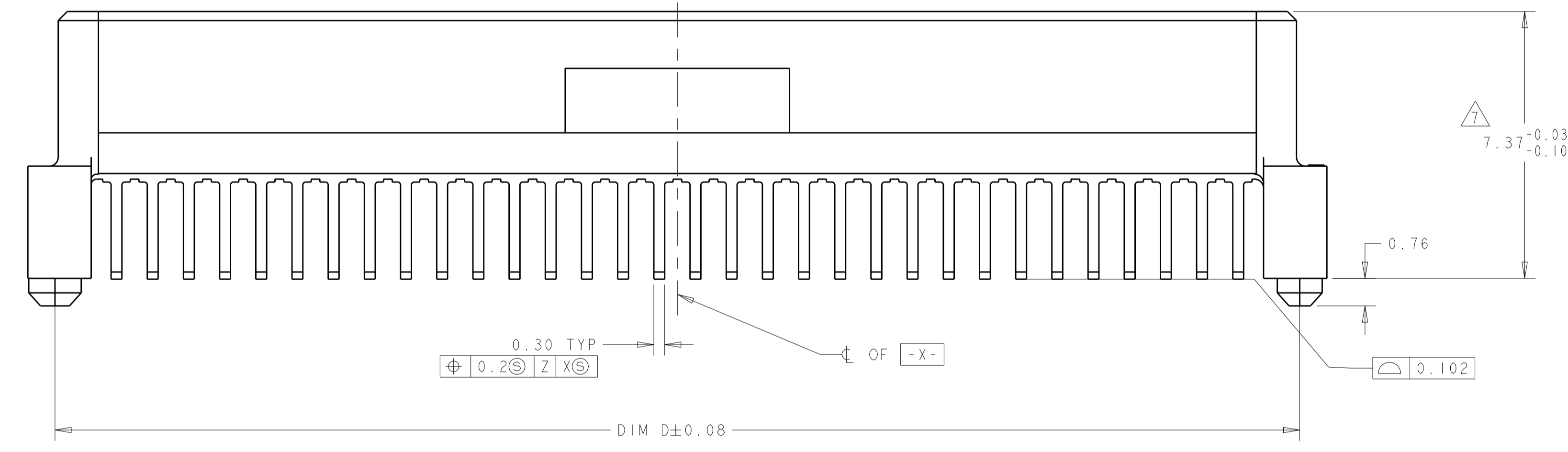
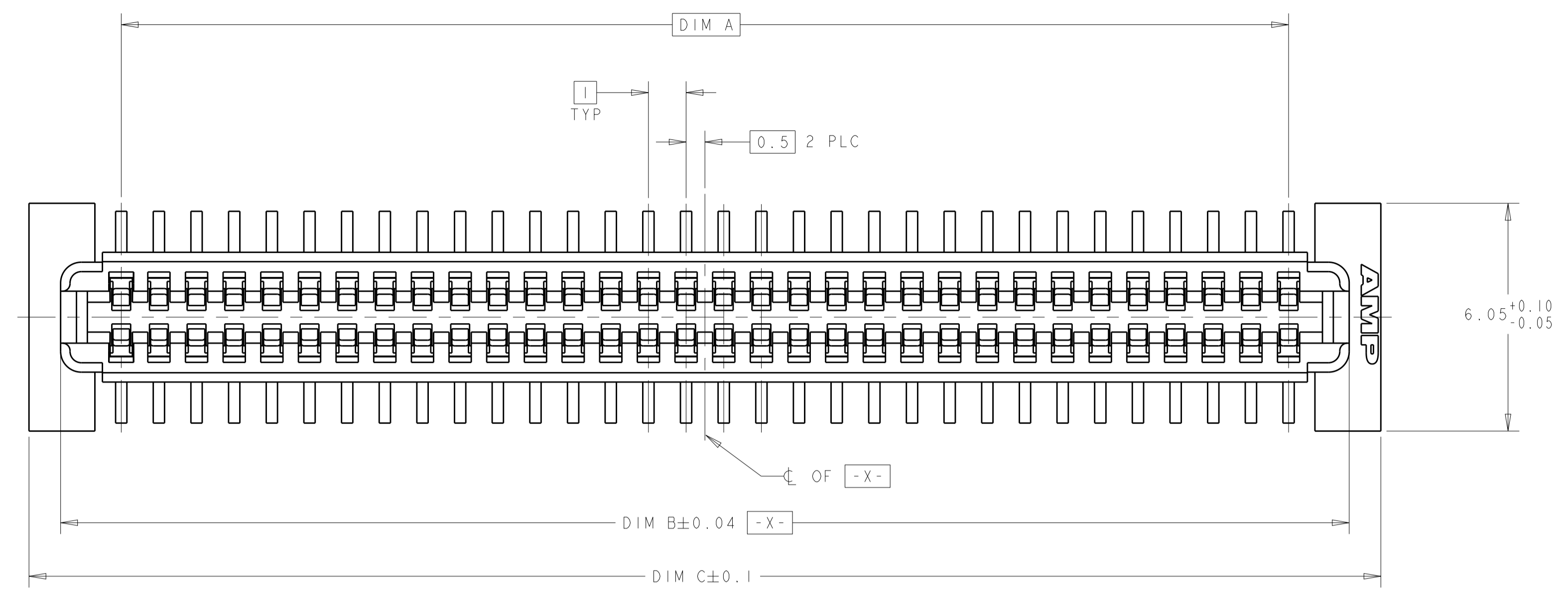
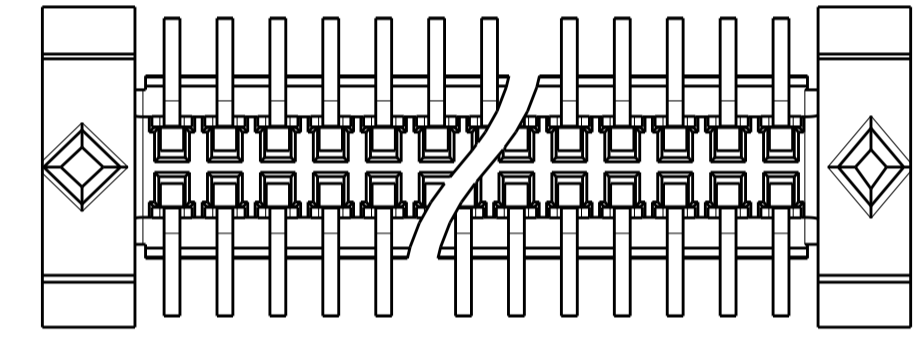


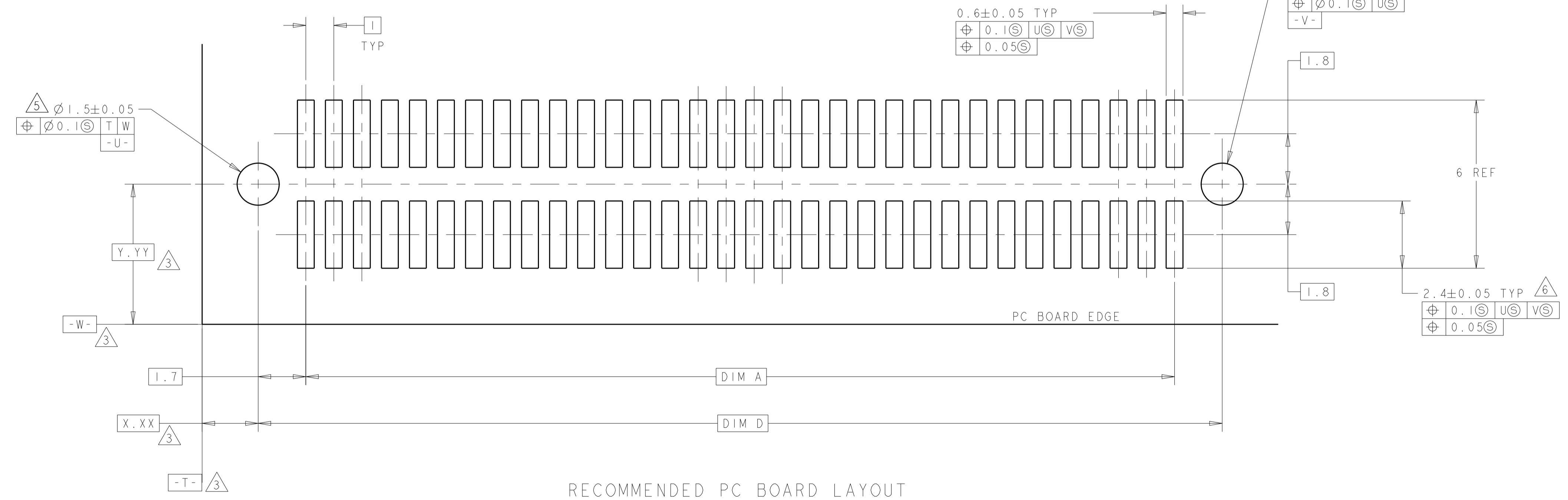
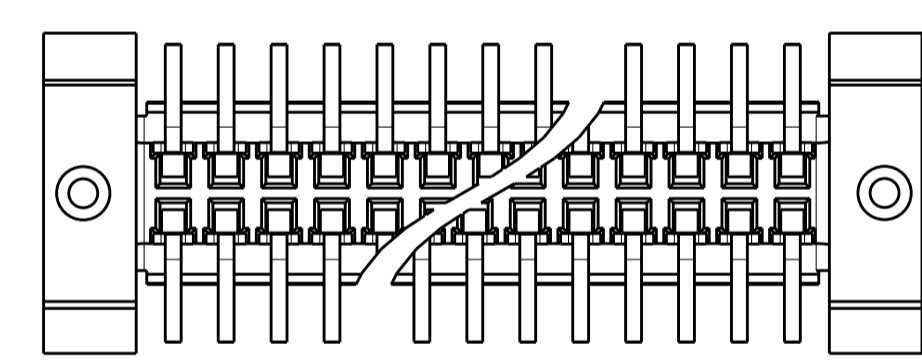
REVISIONS				
REV	DATE	DESCRIPTION	BY	APPV
J	11FEB2015	REV PER ECR-14-016951	I.T	W.H
J1	12MAY2015	REV PER ECR-15-007309	I.T	W.H



9 STYLE A POST



10 STYLE B POST



RECOMMENDED PC BOARD LAYOUT

- HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC. COLOR; BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
- CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PL1 PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
- DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
- PACKAGED IN TAPE ON REEL PER EIA-481.
- 1.5 MIN DIAMETER HOLE SHOULD BE USED IF USING POST STYLE "A" AND PLACING ON PCB WITH VACUUM PLACEMENT EQUIPMENT.
- SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
- REFERRED TO AS DIM H = 7.3±0.1 IN EIA 700AAAB SPECIFICATION.
- CONTACT FINISH: 0.002 MINIMUM BRIGHT TIN-LEAD (93-7) ON SOLDER AREA, 0.00127 MINIMUM GOLD ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
- SQUARE AND DIAMOND SHAPED POSTS
- ROUND SHAPED POSTS

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HGTS	POS	PART NO
10	8	44.4	45.9	44.22	41	11,12	84	3-120603-2
10	10	34.4	35.9	34.22	31	11,12	64	3-120603-1
10	2	44.4	45.9	44.22	41	11,12	84	2-120603-2
9	2	34.4	35.9	34.22	31	11,12	64	2-120603-1
9	8	44.4	45.9	44.22	41	11,12	84	1-120603-2
9	10	34.4	35.9	34.22	31	11,12	64	1-120603-1
9	2	44.4	45.9	44.22	41	11,12	84	120603-2
9	8	34.4	35.9	34.22	31	11,12	64	120603-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN: J. REED 27/17/97. CHK: L. VO 27/17/97.

TE Connectivity

RECEPTACLE ASSY, 1.0mm FH CONNECTOR (IEEE1386)

SCALE: 10:1 SHEET 1 OF 1 REV J1